

LP-MSM050

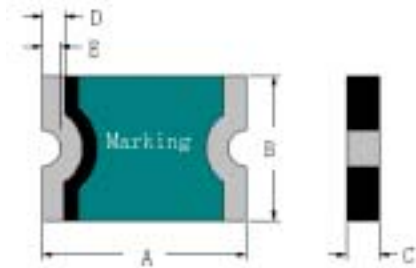
Features

- Small size of 1812
- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly
- Agency Recognition: UL, CSA, TUV

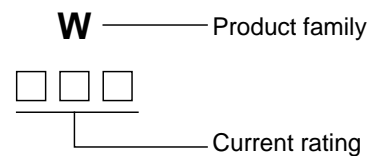


Product Dimensions (mm)

Part number	A	B	C	D	E
	Max.	Max.	Max.	Max.	Min.
LP-MSM050	4.73	3.41	0.61	0.60	0.30



Part Marking System



Electrical Characteristics

Part number	I _H (A)	I _T (A)	V _{max} (V)	I _{max} (A)	T _{trip} Current(A) Time(S)	P _{d typ} (W)	R _{min} ()	R _{1max} ()
LP-MSM050	0.50	1.00	15	40	8.0 0.15	1.0	0.15	1.00

I_H=Hold current: maximum current at which the device will not trip at 25 °C still air.

I_T=Trip current: minimum current at which the device will always trip at 25 °C still air.

V_{max}=Maximum voltage device can withstand without damage at rated current.

I_{max}=Maximum fault current device can withstand without damage at rated voltage.

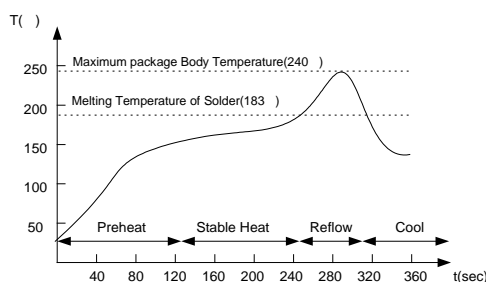
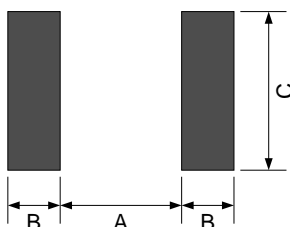
T_{trip}=Maximum time to trip(s) at assigned current.

P_{d typ}=Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

R_{min}=Minimum device resistance at 25 °C prior to tripping.

R_{1max}=Maximum device resistance measured in the nontripped state 1 hour post reflow.

Solder Reflow Recommendations



Solder Pad Layouts

Part number	A (mm)	B (mm)	C (mm)
LP-MSM050	3.45	1.78	3.15

* Recommended reflow methods: IR, Vapor phase oven, hot air oven, wave solder.

* Devices can be cleaned using standard industry methods and solvents.

Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Tape & Reel: 2000pcs per reel.